

MEG-01-004



May 26, 2004

FFW
AF
2827

To: Commissioner for Patents
P.O. Box 1450
Alexandria, VA 22313-1450

Fr: George O. Saile, Reg. No. 19,572
28 Davis Ave
Poughkeepsie, NY 12603

Subject: | Serial No. 09/837,007 04/18/01 |
| Mou-Shiung Lin |
| "A STRUCTURE AND MANUFACTURING |
| METHOD OF A CHIP SCALE PACKAGE" |
Grp. Art Unit: 2827 D. Zarneke

RESPONSE PATENT OFFICE ACTION

Dear Sir:

In response to the Office Action dated March 26, 2004,
please amend the above-identified application for patent as
follows:

CERTIFICATE OF MAILING

I hereby certify that this correspondence is being
deposited with the United States Postal Service as first class
mail in an envelope addressed to: Commissioner for Patents, P.O.
Box 1450, Alexandria, VA 22313-1450, on May 26, 2004.

Stephen B. Ackerman, Reg. No. 37,761

Signature [Signature]
Date 5/26/04